Printed electronics
Application development and volume production

The unique printing technology used, enables a wide range of conductive, non-conductive and biocompatible materials to be printed on a wide range of substrates and forms. In addition, new opportunities exist for interconnect technologies that can lead to performance improvements and cost optimization.

The integration of the circuits into three-dimensional surfaces often eliminates the need to use an additional substrate.

Compared to the methods used today to produce such three-dimensional circuit carriers, the technology chosen by Cicor offers a significantly wider variety of printed and printable materials. Devices for medical, aerospace and IoT applications can be significantly reduced in size by using this technology.
**Technical capabilities**
- Lines/spaces down to 10 µm
- Printing thickness from < 100 nm to tens of µm
- Large material portfolio (conductive, non-conductive, resistors, biocompatible, photoresist, etc.)
- Printing on standard materials
- Efficient printing process

**Possible applications**
- Printed flex and rigid circuits
- Printed embedded passives
- Printed circuits on ceramics (2D + 3D)
- Printed circuits on plastics
- Biocompatible circuits
- Die stacking

*For additional applications please contact our engineering department*

---

**Markets**
- Industrial
- Medical
- Aerospace and defence
- Watches and consumer
- Automotive and transport
- Communication

---

The Cicor Group is a globally active development and manufacturing partner with innovative technology solutions for the electronics industry. With about 2100 employees at ten production sites, Cicor offers highly complex printed circuit boards, printed electronics, hybrid circuits and substrates as well as comprehensive electronic manufacturing services (EMS) including microelectronic assembly and plastic injection molding. Cicor supplies customized products and services from design to the finished product from one source.